

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	159	(resin or metal or ceramic or paper) and hole and "solder ball" and adherent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:32
L2	114	(resin or metal or ceramic or paper) and hole and "solder ball" and adherent and cover	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:32
L3	2	(resin or metal or ceramic or paper) and (hole near4 "solder ball") and adherent and cover	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:39
L4	9	(resin or metal or ceramic or paper) and ((hole or via) near4 "solder ball") and adherent and cover	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:55
L5	0	(resin or metal or ceramic or paper) and ((hole or via) near4 "solder ball") and adherent and cover and (438/616.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:55
L6	2	(resin or metal or ceramic or paper) and ((hole or via) near4 "solder ball") and adherent and cover and (438/613.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:56
L7	2	(resin or metal or ceramic or paper) and ((hole or via) near4 "solder ball") and adherent and cover and (257/780.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:56
S1	162	"solder ball" and (hole or via or trench) and (resin or metal or ceramic or paper) and (acrylic or silicone or rubber) and (polyester or polyimide) and wall	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 12:40

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S2	63	"solder ball" and (hole or via or trench) and (resin or metal or ceramic or paper) and (acrylic or silicone or rubber) and (polyester or polyimide) and wall and cover and plastic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 12:47
S3	13	("solder ball" near8 (hole or via or trench)) and (resin or metal or ceramic or paper) and (acrylic or silicone or rubber) and (polyester or polyimide) and wall and cover and plastic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 14:25
S4	3	("solder ball" near8 (hole or via or trench)) and (resin or metal or ceramic or paper) and (acrylic or silicone or rubber) and (polyester or polyimide) and wall and cover and plastic and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/18 09:15
S5	38	("solder ball" near8 (hole or via or trench)) and (resin or metal or ceramic or paper) and (acrylic or silicone or rubber) and (polyester or polyimide) and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/18 09:15
S6	69	(semiconductor or substrate or wafer) and (dielectric or oxide or nitride) and trench and capacitor and (gate near dielectric) and polysilicon and "CMP" and stud	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 14:28
S7	38	(semiconductor or substrate or wafer) and (dielectric or oxide or nitride) and trench and capacitor and (gate near dielectric) and polysilicon and "CMP" and stud and "CVD"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 14:38
S8	6	(semiconductor or substrate or wafer) and (dielectric or oxide or nitride) and trench and capacitor and (gate near dielectric) and polysilicon and "CMP" and (polysilicon near4 stud) and "CVD"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 08:03
S9	12	(semiconductor or substrate or wafer) and (dielectric or oxide or nitride) and trench and capacitor and (gate near dielectric) and polysilicon and "CMP" and (polysilicon near4 stud)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 08:28

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S10	25	(polysilicon near stud) and (substrate or wafer or semiconductor) and (dielectric or oxide or nitride) and trench and (gate near4 dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 08:30
S11	9	(polysilicon near stud) and (substrate or wafer or semiconductor) and (dielectric or oxide or nitride) and trench and (gate near4 dielectric) and "cmp"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/23 08:49
S12	6	(polysilicon near stud) and (substrate or wafer or semiconductor) and (dielectric or oxide or nitride) and trench and (gate near4 dielectric) and "cmp" and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 10:28